



ALPHA & OMEGA
SEMICONDUCTOR

AOTF380A60L/AOT380A60L/AOB380A60L
600V, α MOSSTM N-Channel Power Transistor

General Description

- Proprietary α MOSSTM technology
- Low $R_{DS(ON)}$
- Optimized switching parameters for better EMI performance
- Enhanced body diode for robustness and fast reverse recovery

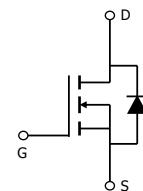
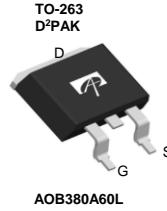
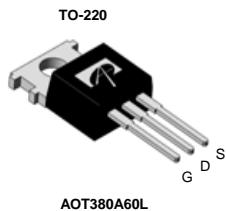
Applications

- SMPS with PFC, Flyback and LLC topologies
- Silver ATX, adapter, TV, lighting, Server power

Product Summary

V_{DS} @ $T_{j,max}$	700V
I_{DM}	44A
$R_{DS(ON),max}$	< 0.38Ω
$Q_{g,typ}$	18nC
E_{oss} @ 400V	2.6μJ

100% UIS Tested
100% R_g Tested



Orderable Part Number	Package Type	Form	Minimum Order Quantity
AOT380A60L	TO-220 Green	Tube	1000
AOTF380A60L	TO-220F Green	Tube	1000
AOB380A60L	TO263	Tape and reel	800

Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	AOT(B)380A60L	AOTF380A60L	Units
Drain-Source Voltage	V_{DS}	600		V
Gate-Source Voltage	V_{GS}		± 20	V
Gate-Source Voltage (dynamic) AC(f>1Hz)	V_{GS}		± 30	V
Continuous Drain Current ^A $T_c=25^\circ\text{C}$	I_D	11	11*	A
Continuous Drain Current ^A $T_c=100^\circ\text{C}$		7.2	7.2*	
Pulsed Drain Current ^C	I_{DM}	44		
Avalanche Current ^C	I_{AR}	2.5		A
Repetitive avalanche energy ^C	E_{AR}	3.1		mJ
Single pulsed avalanche energy ^G ($T_j=25^\circ\text{C}$, $V_{GS}=10\text{V}$, $I_L=2\text{Apk}$, $L=105\text{mH}$, $R_{GS}=25\Omega$)	E_{AS}	210		mJ
MOSFET dv/dt ruggedness	dv/dt	100		V/ns
Peak diode recovery dv/dt		20		
Power Dissipation ^B $T_c=25^\circ\text{C}$	P_D	131	27	W
Derate above 25°C		1.0	0.2	W/ $^\circ\text{C}$
Junction and Storage Temperature Range	T_J , T_{ST}	-55 to 150		$^\circ\text{C}$
Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds	T_L	300		$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	AOT(B)380A60L	AOTF380A60L	Units
Maximum Junction-to-Ambient ^{A,D}	R_{JJA}	65	65	$^\circ\text{C/W}$
Maximum Case-to-sink ^A	R_{ICS}	0.5	--	$^\circ\text{C/W}$
Maximum Junction-to-Case	R_{JJC}	0.95	4.6	$^\circ\text{C/W}$

* Drain current limited by maximum junction temperature.

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0V, T _J =25°C	600			V
		I _D =250μA, V _{GS} =0V, T _J =150°C		700		
BV _{DSS} /ΔT _J	Breakdown Voltage Temperature Coefficient	I _D =250μA, V _{GS} =0V		0.44		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =600V, V _{GS} =0V		1		μA
		V _{DS} =480V, T _J =125°C		10		
I _{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} =±20V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =5V, I _D =250μA	2.6	3.2	3.8	V
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =5.5A		0.33	0.38	Ω
g _{FS}	Forward Transconductance	V _{DS} =10V, I _D =5.5A		9.3		S
V _{SD}	Diode Forward Voltage	I _S =5.5A, V _{GS} =0V		0.85	1.2	V
I _S	Maximum Body-Diode Continuous Current				11	A
I _{SM}	Maximum Body-Diode Pulsed Current ^C				44	A
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =100V, f=1MHz		955		pF
C _{oss}	Output Capacitance			29		pF
C _{o(er)}	Effective output capacitance, energy related ^H	V _{GS} =0V, V _{DS} =0 to 480V, f=1MHz		30		pF
C _{o(tr)}	Effective output capacitance, time related ^I			122		pF
C _{rss}	Reverse Transfer Capacitance	V _{GS} =0V, V _{DS} =100V, f=1MHz		2.4		pF
R _g	Gate resistance	f=1MHz		4.8		Ω
SWITCHING PARAMETERS						
Q _g	Total Gate Charge	V _{GS} =10V, V _{DS} =480V, I _D =5.5A		18		nC
Q _{gs}	Gate Source Charge			7		nC
Q _{gd}	Gate Drain Charge			4.5		nC
t _{D(on)}	Turn-On DelayTime	V _{GS} =10V, V _{DS} =400V, I _D =5.5A, R _G =5Ω		20		ns
t _r	Turn-On Rise Time			13		ns
t _{D(off)}	Turn-Off DelayTime			43		ns
t _f	Turn-Off Fall Time			16		ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =5.5A, dI/dt=100A/μs, V _{DS} =400V		251		ns
I _{rm}	Peak Reverse Recovery Current			19		A
Q _{rr}	Body Diode Reverse Recovery Charge			3.1		μC

A. The value of R_{JA} is measured with the device in a still air environment with T_A=25°C.

B. The power dissipation P_D is based on T_{J(MAX)}=150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150°C. Ratings are based on low frequency and duty cycles to keep initial T_J=25°C.

D. The R_{JA} is the sum of the thermal impedance from junction to case R_{JJC} and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T_{J(MAX)}=150°C. The SOA curve provides a single pulse rating.

G. This is the absolute maximum rating. Parts are 100% tested at T_J=25°C, L=60mH, I_{AS}=1A, V_{DD}=150V, R_G=25Ω.

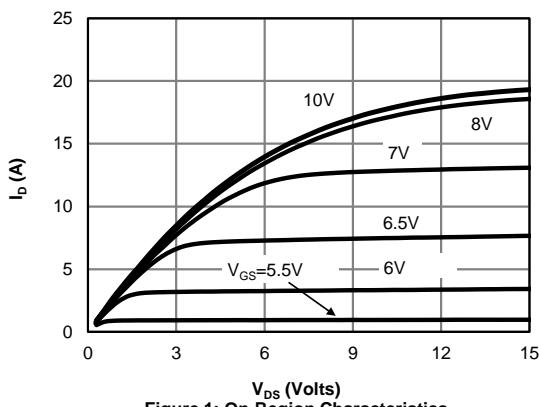
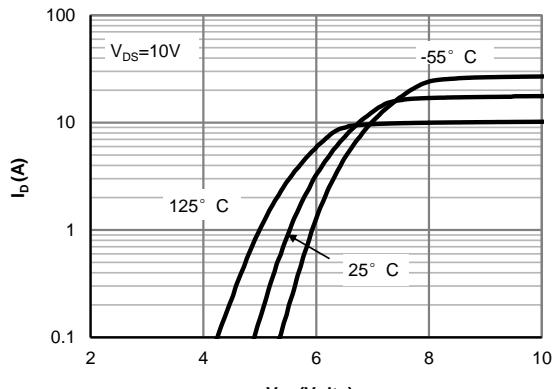
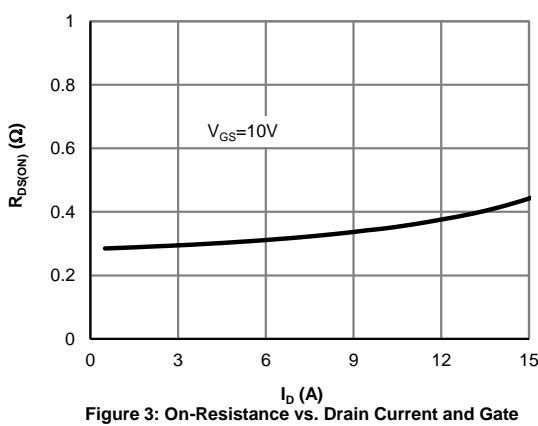
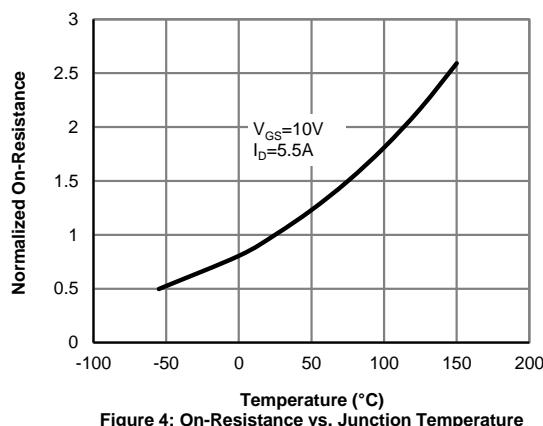
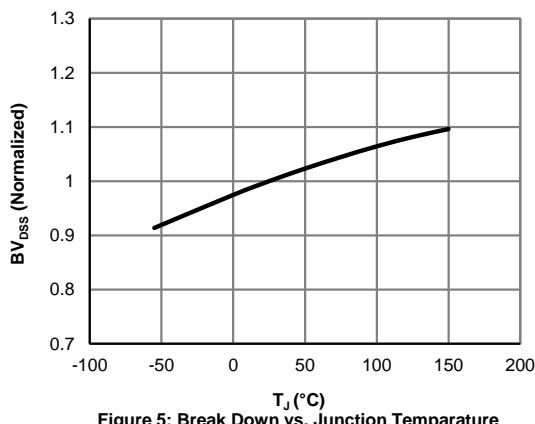
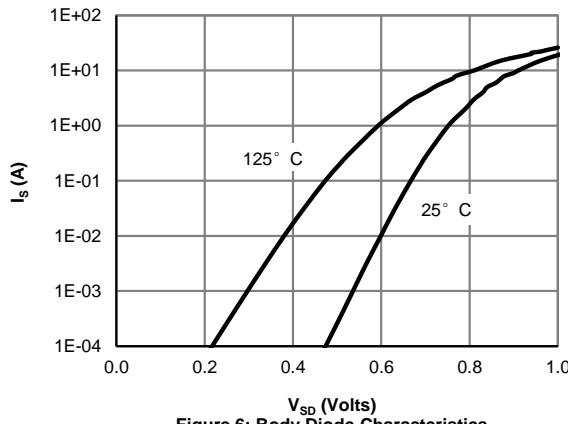
H. C_{o(er)} is a fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% V_{(BR)DSS}.

I. C_{o(tr)} is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{(BR)DSS}.

APPLICATIONS OR USES AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS ARE NOT AUTHORIZED. AOS DOES NOT ASSUME ANY LIABILITY ARISING OUT OF SUCH APPLICATIONS OR USES OF ITS PRODUCTS. AOS RESERVES THE RIGHT TO MAKE CHANGES TO PRODUCT SPECIFICATIONS WITHOUT NOTICE. IT IS THE RESPONSIBILITY OF THE CUSTOMER TO EVALUATE SUITABILITY OF THE PRODUCT FOR THEIR INTENDED APPLICATION. CUSTOMER SHALL COMPLY WITH APPLICABLE LEGAL REQUIREMENTS, INCLUDING ALL APPLICABLE EXPORT CONTROL RULES, REGULATIONS AND LIMITATIONS.

AOS' products are provided subject to AOS' terms and conditions of sale which are set forth at:

http://www.aosmd.com/terms_and_conditions_of_sale

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 1: On-Region Characteristics

Figure 2: Transfer Characteristics

Figure 3: On-Resistance vs. Drain Current and Gate Voltage

Figure 4: On-Resistance vs. Junction Temperature

Figure 5: Break Down vs. Junction Temperature

Figure 6: Body-Diode Characteristics

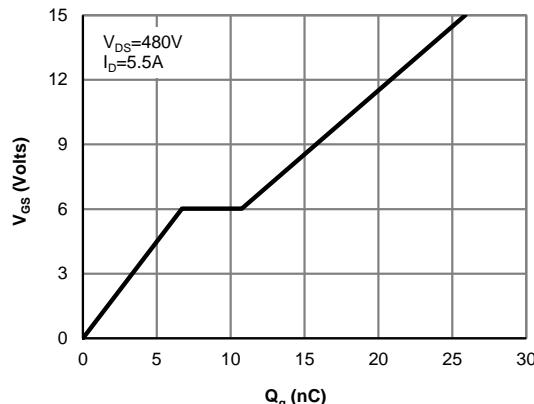
TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS


Figure 7: Gate-Charge Characteristics

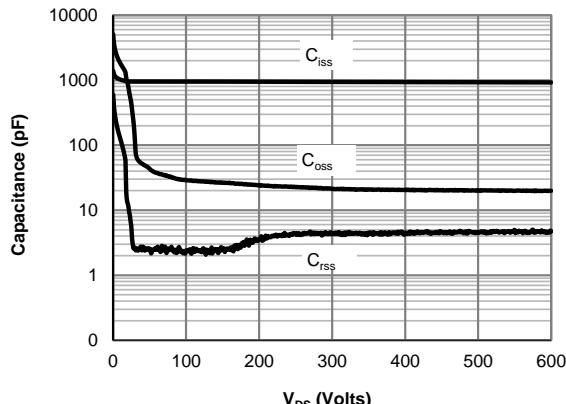


Figure 8: Capacitance Characteristics

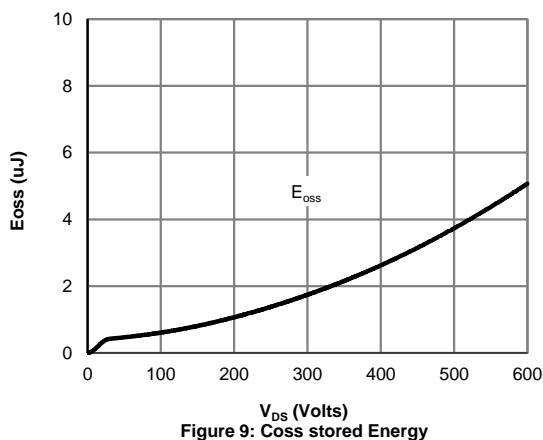
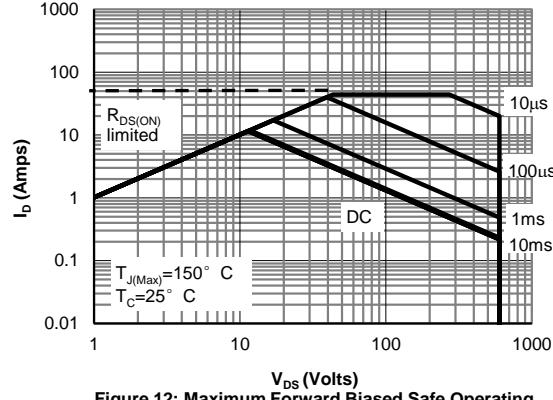
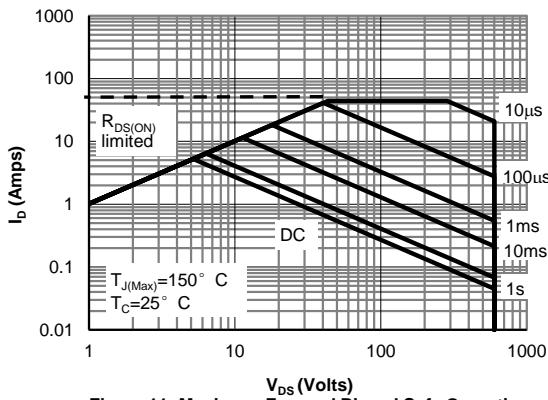
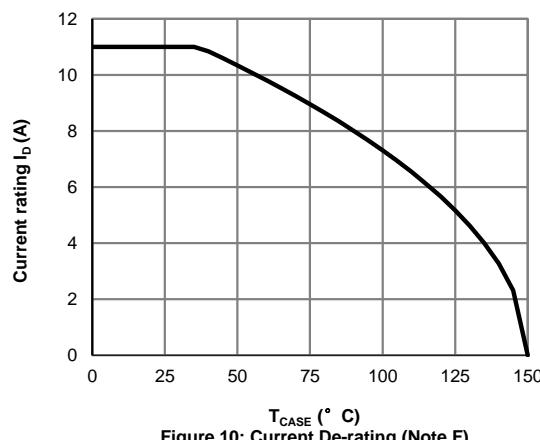


Figure 9: Coss stored Energy



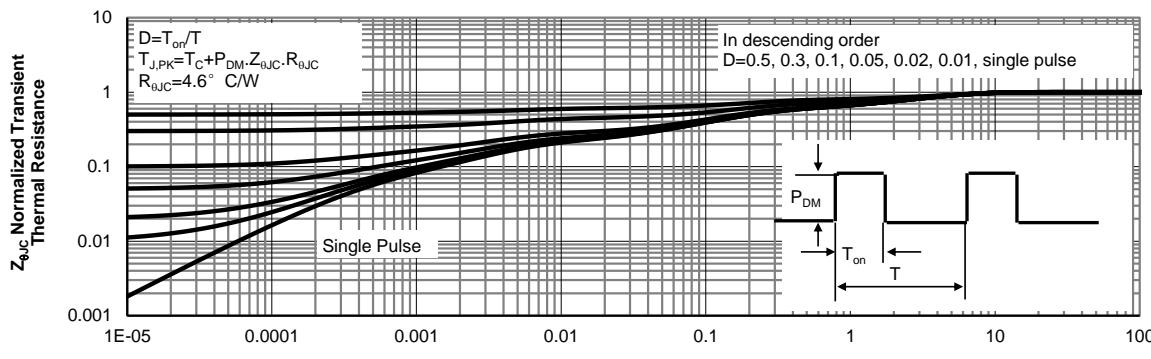
TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS


Figure 13: Normalized Maximum Transient Thermal Impedance for AOTF380A60L (Note F)

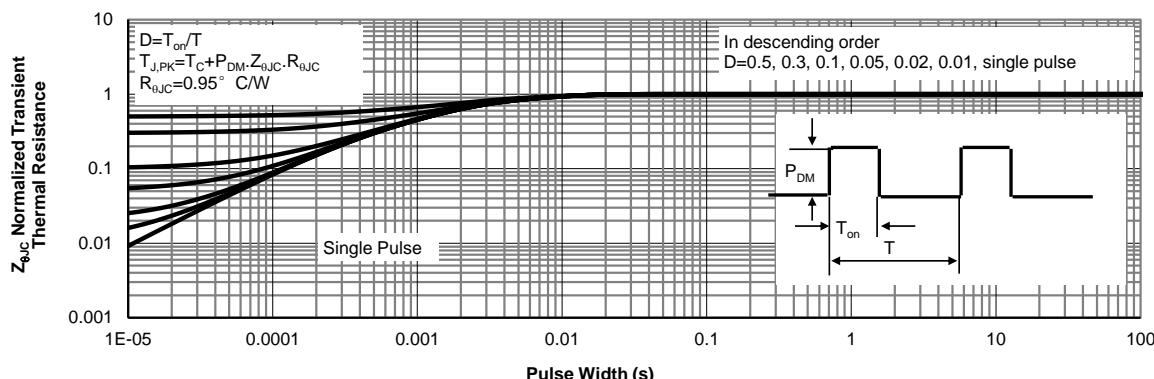
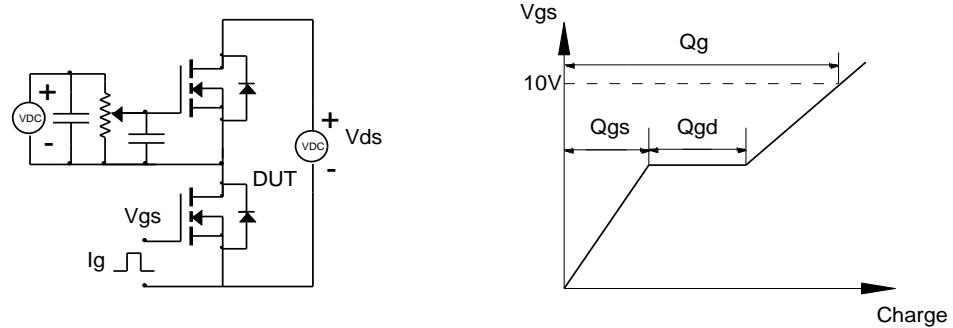
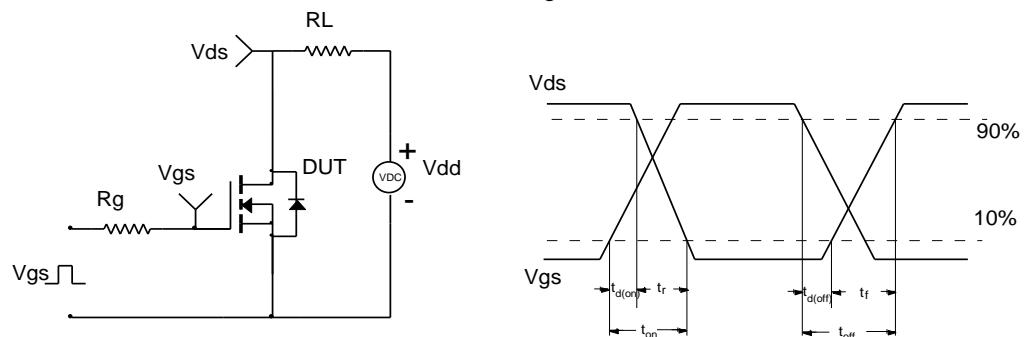
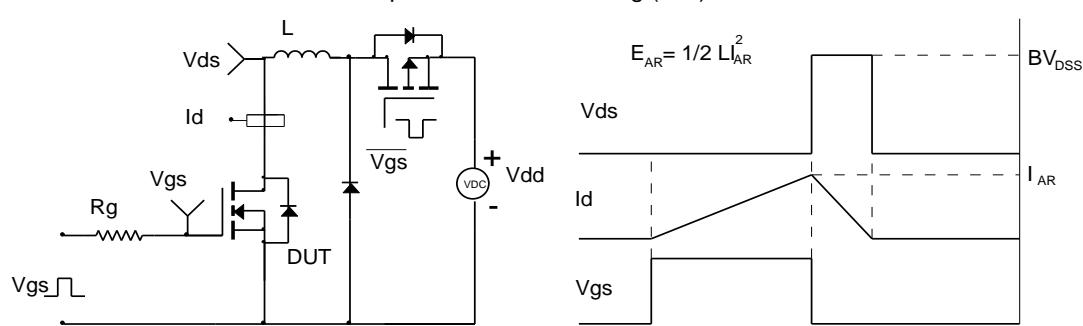


Figure 14: Normalized Maximum Transient Thermal Impedance for AOT(B)380A60L (Note F)

Gate Charge Test Circuit & Waveform

Resistive Switching Test Circuit & Waveforms

Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

Diode Recovery Test Circuit & Waveforms
